



Material Composition Declaration

EPC2204

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/12/2023
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	5.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.3254	78.6288	81.9211	786288
	Silicon oxide	7631-86-9	0.0279	0.5079		5079
	Silicon nitride	12033-89-5	0.0083	0.1504		1504
	Gallium nitride	25617-97-4	0.0215	0.3914		3914
	Aluminum	7429-90-5	0.0417	0.7589		7589
	Aluminum nitride	24304-00-5	0.0046	0.0831		831
	Titanium	7440-32-6	0.0009	0.0162		162
	Titanium nitride	25583-20-4	0.0374	0.6794		6794
	Copper	7440-50-8	0.0007	0.0127		127
	Tungsten	7440-33-7	0.0050	0.0908		908
	Polyimide		0.0331	0.6016		6016
Under Bump Metal	Titanium	7440-32-6	0.0007	0.0122	0.1338	122
	Copper	7440-50-8	0.0067	0.1215		1215
Solder Bump	Copper	7440-50-8	0.0669	1.2153	17.9451	12153
	Nickel	7440-02-0	0.0399	0.7249		7249
	Tin	7440-31-5	0.8646	15.7168		157168
	Silver	7440-22-4	0.0158	0.2881		2881
Sum in total:			5.5010	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.